

<b>L Number</b>	<b>Hits</b>	<b>Search Text</b>	<b>DB</b>	<b>Time stamp</b>
<b>1</b>	<b>418</b>	<b>graybill.xp.xa.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/27 20:02</b>
<b>2</b>	<b>933040</b>	<b>chip die</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/27 20:02</b>
<b>3</b>	<b>301</b>	<b>graybill.xp.xa. and (chip die)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/27 20:12</b>
<b>4</b>	<b>7</b>	<b>("4835598"   "5130771"   "5640048"   "5959356"   "6206997"   "6282094"   "6325272").PN.</b>	<b>USPAT</b>	<b>2003/08/27 20:05</b>
<b>5</b>	<b>0</b>	<b>6528882.URPN.</b>	<b>USPAT</b>	<b>2003/08/27 20:06</b>
<b>6</b>	<b>0</b>	<b>6528882.URPN.</b>	<b>USPAT</b>	<b>2003/08/27 20:06</b>
<b>7</b>	<b>241</b>	<b>graybill.xa.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/27 20:13</b>
<b>8</b>	<b>186</b>	<b>graybill.xa. and (chip die)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/27 20:13</b>
<b>9</b>	<b>5</b>	<b>("4786954"   "4972248"   "5286671"   "5298767"   "5666833").PN.</b>	<b>USPAT</b>	<b>2003/08/27 20:17</b>
<b>10</b>	<b>10</b>	<b>5401672.URPN.</b>	<b>USPAT</b>	<b>2003/08/27 20:18</b>
<b>11</b>	<b>7</b>	<b>("4394712"   "4893174"   "4939568"   "5034347"   "5401672"   "5447871"   "5627106").PN.</b>	<b>USPAT</b>	<b>2003/08/27 20:24</b>
<b>-</b>	<b>286</b>	<b>257/276</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/22 18:47</b>
<b>-</b>	<b>13</b>	<b>(circular adj pads) with ((square rectangular) adj pads)</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/08/25 14:10</b>

-	253	257/276 n t (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 14:14
-	0	(thermal! adj via) and (257/276 not (@ad>20010520 @rlad>20010520 @pt1d>20010520))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 14:15
-	2279077	via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 14:15
-	158	(257/276 not (@ad>20010520 @rlad>20010520 @pt1d>20010520)) and via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 17:17
-	7865	calorific adj value	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 17:17
-	0	(calorific adj value) and (257/276 not (@ad>20010520 @rlad>20010520 @pt1d>20010520))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 17:17
-	617766	transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 17:17
-	166	(calorific adj value) and transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 17:18
-	148	((calorific adj value) and transistor) not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 18:22
-	54641	bipolar adj transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 18:24

-	66629	heatsink heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 18:24
-	91	(bipolar adj transistor) with (heatsink heat adj sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 18:25
-	81	((bipolar adj transistor) with (heatsink heat adj sink)) not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 18:32
-	94	(257/276 not (@ad>20010520 @rlad>20010520 @pt1d>20010520)) not (((257/276 not (@ad>20010520 @rlad>20010520 @pt1d>20010520)) and via) ((calorific adj value) and transistor) (((bipolar adj transistor) with (heatsink heat adj sink)) not (@ad>20010520 @rlad>20010520 @pt1d>20010520)) (@ad>20010520 @rlad>20010520 @pt1d>20010520))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 19:00
-	1	"5757081".PN.	USPAT	2003/08/25 18:48
-	9	("4764804"   "4972250"   "5091331"   "5170930"   "5229643"   "5272104"   "5352926"   "5397917"   "5426072").PN.	USPAT	2003/08/25 18:49
-	40	("3256465"   "3343256"   "3372070"   "3418545"   "3445686"   "3454835"   "3456335"   "3462650"   "3648131"   "3796927"   "3798513"   "3885196"   "3959579"   "3962052"   "3969745"   "3982268"   "4074342"   "4097890"   "4104674"   "4188709"   "4263341"   "4275410"   "4368503"   "4379307"   "4467343"   "4528072"   "4613891"   "4670764"   "4720738"   "4761681"   "4839510"   "4862322"   "4897708"   "4939568"   "4954875"   "5198695"   "5200631"   "5202754"   "5404044"   "5481133").PN.	USPAT	2003/08/25 18:51
-	27	("2627545"   "2734154"   "3197766"   "3475660"   "3561110"   "3648131"   "3769702"   "3813773"   "3858958"   "3867759"   "3904934"   "3967162"   "3999105"   "4029375"   "4037246"   "4050756"   "4129881"   "4295700"   "4368106"   "4394712"   "4437109"   "4499655"   "4509099"   "4558396"   "4574331"   "4581679"   "4596069").PN.	USPAT	2003/08/25 18:57

-	56	3648131.URPN.	USPAT	2003/08/25 19:00
-	56	3648131.URPN. n t (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/08/25 19:07
-	1	"3969745".PN.	USPAT	2003/08/25 19:09
-	5	5438212.URPN.	USPAT	2003/08/25 19:09
-	111	(thermal! adj via) and transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 19:10
-	89	((thermal! adj via) and transistor) not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 12:36
-	7	("4739448"   "5182632"   "5485036"   "5703753"   "5719750"   "5825628"   "5990545").PN.	USPAT	2003/08/25 19:27
-	1	2002-476940.NRAN.	DERWENT	2003/08/25 19:49
-	1	1998-545315.NRAN.	DERWENT	2003/08/25 19:52
-	10	2325082.URPN.	USPAT	2003/08/25 19:53
-	179	257/625	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:04
-	167	257/502	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:04
-	1401359	@ad>20010520 @rlad>20010520 @pt1d>20010520	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:05
-	152	257/502 not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:10

-	237	257/579	U PAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:10
-	229	257/579 not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:11
-	596648	stagger\$ offset\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:11
-	16	(257/579 not (@ad>20010520 @rlad>20010520 @pt1d>20010520)) and (stagger\$ offset\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:13
-	322715	257/\$.ccls. 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:16
-	3036402	heat thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:17
-	16090	(stagger\$ offset\$) with (heat thermal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:18
-	828	(257/\$.ccls. 438/\$.ccls.) and ((stagger\$ offset\$) with (heat thermal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:18
-	593656	transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:18
-	338	((257/\$.ccls. 438/\$.ccls.) and ((stagger\$ offset\$) with (heat thermal))) and transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:23

-	139	257/164	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:23
-	7421	257/163-166,197,198,557-593,e29.03,e29.011,e29.012,ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:29
-	13	((stagger\$ offset\$) with (heat thermal)) and 257/163-166,197,198,557-593,e29.03,e29.011,e29.012,ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:30
-	12	(((stagger\$ offset\$) with (heat thermal)) and 257/163-166,197,198,557-593,e29.03,e29.011,e29.012,ccls.) not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:41
-	7	("2929006"   "3252063"   "3582723"   "3783349"   "3878550"   "4441116"   "4618781").PN.	USPAT	2003/08/26 13:33
-	7	5003370.URPN.	USPAT	2003/08/26 13:52
-	1		USPAT	2003/08/26 13:55
-	615981	plated adj heat! adj sink phs	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:42
-	594568	transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:42
-	5622	(plated adj heat! adj sink phs) and transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:43
-	1460204	semiconductor (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:43
-	1475199	semiconductor integrated adj circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:44

-	17649	semi ndu t r adj circuit	U PAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:45
-	1442912	(semiconductor (integrated adj circuit)) not (semiconductor adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:45
-	1457550	(semiconductor integrated adj circuit) not (semiconductor adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:46
-	14995	(semiconductor integrated adj circuit) not (semiconductor (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 17:03
-	0	(semiconductor (integrated adj circuit)) not (semiconductor integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 17:03
-	564	thermall adj via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 17:39
-	15	(plated adj heatl adj sink phs) and (thermal! adj via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 17:39
-	12	((plated adj heatl adj sink phs) and (thermal! adj via)) not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 17:53
-	8458	257/706,707,712-722.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 17:54
-	85	(thermal! adj via) and 257/706,707,712-722.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 17:54

-	75	((thermall adj via) and 257/706,707,712-722.ccls.) n t (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 18:14
-	49	(plated adj heat! adj sink phs) and 257/706,707,712-722.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 18:14
-	44	((plated adj heat! adj sink phs) and 257/706,707,712-722.ccls.) not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 18:14
-	2	5864169.URPN.	USPAT	2003/08/26 18:19
-	1	"5757081".PN.	USPAT	2003/08/26 18:27
-	0	6259156.URPN.	USPAT	2003/08/26 18:28
-	47	shirakawa-kazuhiko.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 20:02